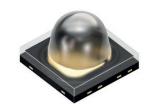
SFH 4718A

OSLON® Black

OSLON Black Series (850 nm) - 40°









Applications

- Access Control (IRIS/Vein Scan, Face Recognition)
- CCTV Surveillance

- Gaming, Amusement, Gambling
- Safety and Security, CCTV

Features:

- Package: diffuse silicone
- Corrosion Robustness Class: 3B
- ESD: 2 kV acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)
- IR lightsource with high efficiency
- Low thermal resistance (Max. 16 K/W)
- Centroid wavelength 850 nm

Ordering Information

Туре	Radiant intensity ¹⁾ $I_{F} = 1 \text{ A; } t_{p} = 10 \text{ ms}$ I_{e}	Radiant intensity ¹⁾ typ. $I_F = 1 \text{ A}; t_p = 10 \text{ ms}$ I_e	Ordering Code
SFH 4718A	400 1000 mW/sr	730 mW/sr	Q65112A1520



Maximum Ratings

T_A = 25 °C

Parameter	Symbol		Values
Operating temperature	T _{op}	min. max.	-40 °C 125 °C
Storage temperature	T_{stg}	min. max.	-40 °C 125 °C
Junction temperature	T _j	max.	145 °C
Forward current	I _F	max.	1000 mA
Surge current D ≤ 1	I _{FSM}	max.	1 A
Reverse voltage 2)	V_R	max.	12 V
Power consumption	P _{tot}	max.	2.3 W
ESD withstand voltage acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)	V_{ESD}	max.	2 kV

For the forward current and power consumption please see "maximum permissible forward current" diagram



Characteristics

 $I_{_{\rm F}}$ = 1000 mA; $t_{_{
m D}}$ = 10 ms; $T_{_{
m A}}$ = 25 °C

Parameter	Symbol		Values
Peak wavelength	λ_{peak}	typ.	860 nm
Centroid wavelength	$\lambda_{ ext{centroid}}$	typ.	850 nm
Spectral bandwidth at 50% I _{rel,max}	Δλ	typ.	34 nm
Half angle	φ	typ.	20 °
Dimensions of active chip area	LxW	typ.	0.75 x 0.75 mm x mm
Rise time (10% / 90%) $I_F = 1 \text{ A}; R_L = 50 \Omega$	t _r	typ.	11 ns
Fall time (10% / 90%) $I_F = 1 \text{ A}; R_L = 50 \Omega$	t _f	typ.	15 ns
Forward voltage	V _F	typ. max.	1.75 V 2.3 V
Reverse current ²⁾ V _R = 5 V	I _R	max. typ.	10 μA 0.01 μA
Total radiant flux $^{3)}$ I _F = 1 A; t _p = 100 µs	Фе	typ.	665 mW
Temperature coefficient of voltage	TC_v	typ.	-1 mV / K
Temperature coefficient of brightness	TC	typ.	-0.3 % / K
Temperature coefficient of wavelength	TC_{λ}	typ.	0.3 nm / K
Thermal resistance junction solder point real 4)	R_{thJS}	max.	16 K / W

Brightness Groups

T_A = 25 °C

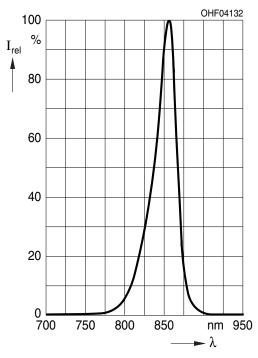
Group	Radiant intensity $I_F = 1000 \text{ mA}$; $t_p = 10 \text{ ms}$ min. I_e	Radiant intensity $I_F = 1000 \text{ mA}$; $t_p = 10 \text{ ms}$ max. I_e
DA	400 mW/sr	630 mW/sr
DB	500 mW/sr	800 mW/sr
EA	630 mW/sr	1000 mW/sr

Only one group in one packing unit (variation lower 1.6:1).



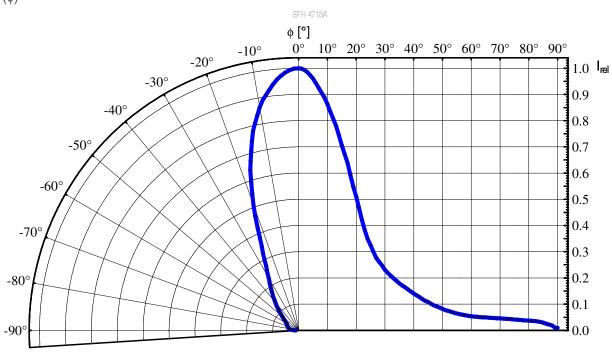
Relative Spectral Emission 5), 6)

 $I_{rel} = f(\lambda); I_F = 1000 \text{ mA}; t_p = 10 \text{ ms}$



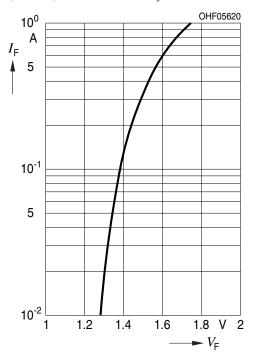
Radiation Characteristics 5), 6)

 $I_{rel} = f(\phi)$



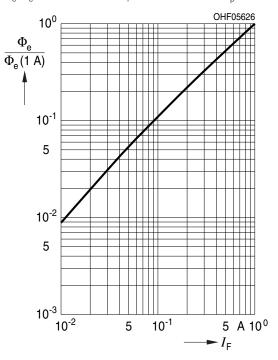
Forward current 5), 6)

 $I_F = f(V_F)$; single pulse; $t_p = 100 \mu s$



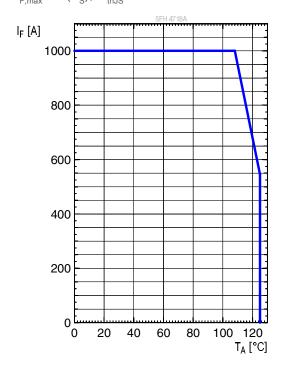
Relative Total Radiant Flux 5), 6)

 Φ_e/Φ_e (1000mA) = f (I_F); single pulse; t_o = 100 µs

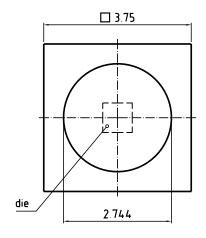


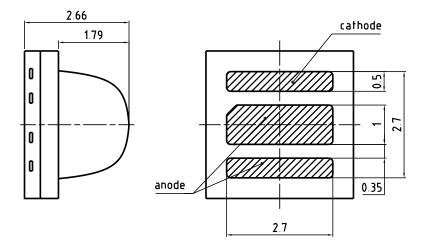
Max. Permissible Forward Current

$$I_{F,max} = f(T_S); R_{thJS} = 16 K/W$$



Dimensional Drawing 7)





general tolerance ± 0.1 lead finish Au

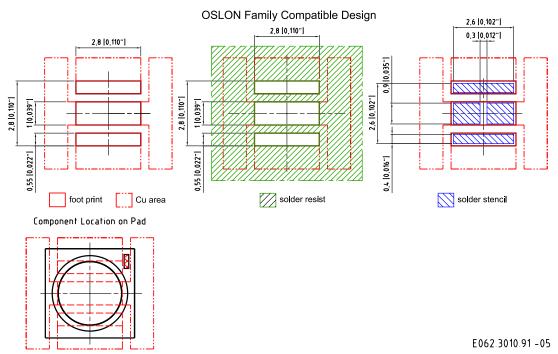
C63062-A4141-A15-02

Approximate Weight:31.0 mgPackage marking:CathodeCorrosion test:Class: 3B

Test condition: 40° C / 90 % RH / 15 ppm H₂S / 14 days (stricter then IEC

60068-2-43)

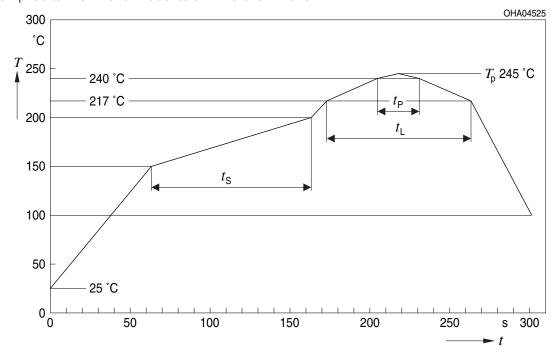
Recommended Solder Pad 7)



For superior solder joint connectivity results we recommend soldering under standard nitrogen atmosphere. Package not suitable for ultra sonic cleaning.

Reflow Soldering Profile

Product complies to MSL Level 2 acc. to JEDEC J-STD-020E

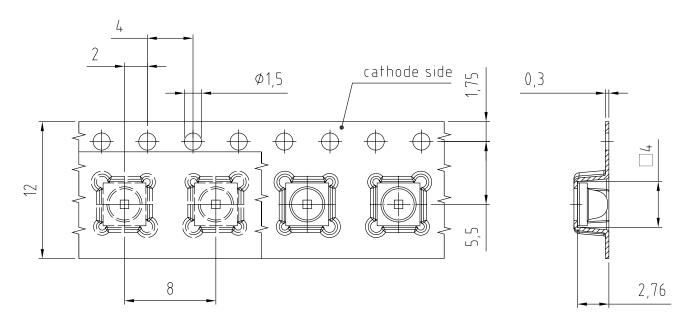


SFH 4718A

Profile Feature	Symbol	Pb	-Free (SnAgCu) Ass	sembly	Unit
	,	Minimum	Recommendation	Maximum	
Ramp-up rate to preheat*) 25 °C to 150 °C			2	3	K/s
Time t_s T_{Smin} to T_{Smax}	t _s	60	100	120	S
Ramp-up rate to peak*) T_{Smax} to T_{P}			2	3	K/s
Liquidus temperature	T_L		217		°C
Time above liquidus temperature	t_		80	100	S
Peak temperature	T _P		245	260	°C
Time within 5 °C of the specified peak temperature T _P - 5 K	t _P	10	20	30	S
Ramp-down rate* T _p to 100 °C			3	6	K/s
Time 25 °C to T _P				480	S

All temperatures refer to the center of the package, measured on the top of the component * slope calculation DT/Dt: Dt max. 5 s; fulfillment for the whole T-range

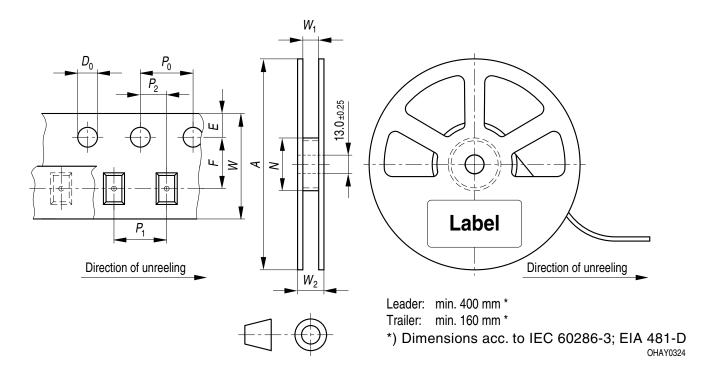
Taping 7)



C63062-A4141-B15 -01



Tape and Reel 8)



Reel dimensions [mm]

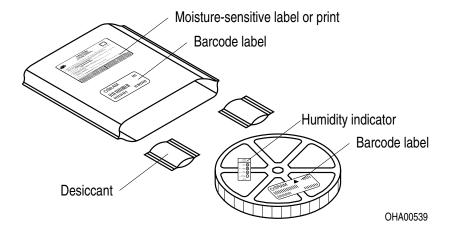
A	W	N_{min}	W_1	$W_{2 \text{max}}$	Pieces per PU
180 mm	12 + 0.3 / - 0.1	60	12.4 + 2	18.4	600



Barcode-Product-Label (BPL)



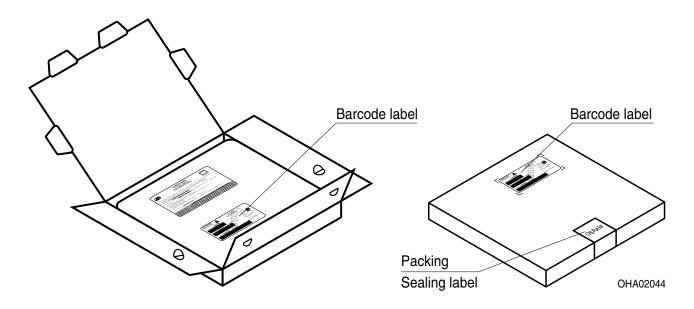
Dry Packing Process and Materials 7)



Moisture-sensitive product is packed in a dry bag containing desiccant and a humidity card according JEDEC-STD-033.



Transportation Packing and Materials 7)



Dimensions of transportation box in mm

Width	Length	Height
195 ± 5 mm	195 ± 5 mm	30 ± 5 mm



Notes

The evaluation of eye safety occurs according to the standard IEC 62471:2006 (photo biological safety of lamps and lamp systems). Within the risk grouping system of this IEC standard, the device specified in this data sheet falls into the class **exempt group (exposure time 10000 s)**. Under real circumstances (for exposure time, conditions of the eye pupils, observation distance), it is assumed that no endangerment to the eye exists from these devices. As a matter of principle, however, it should be mentioned that intense light sources have a high secondary exposure potential due to their blinding effect. When looking at bright light sources (e.g. headlights), temporary reduction in visual acuity and afterimages can occur, leading to irritation, annoyance, visual impairment, and even accidents, depending on the situation.

Subcomponents of this LED contain, in addition to other substances, metal filled materials including silver. Metal filled materials can be affected by environments that contain traces of aggressive substances. Therefore, we recommend that customers minimize LED exposure to aggressive substances during storage, production, and use. LEDs that showed visible discoloration when tested using the described tests above did show no performance deviations within failure limits during the stated test duration. Respective failure limits are described in the IEC60810.

For further application related informations please visit www.osram-os.com/appnotes



Disclaimer

Disclaimer

Language english will prevail in case of any discrepancies or deviations between the two language wordings.

Attention please!

The information describes the type of component and shall not be considered as assured characteristics. Terms of delivery and rights to change design reserved. Due to technical requirements components may contain dangerous substances.

For information on the types in question please contact our Sales Organization.

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Packing

Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office

By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

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Glossary

- Radiant intensity: Measured at a solid angle of $\Omega = 0.01 \text{ sr}$
- Reverse Operation: Reverse Operation of 10 hours is permissible in total. Continuous reverse operation is not allowed.
- Total radiant flux: Measured with integrating sphere.
- Thermal resistance: junction soldering point, of the device only, mounted on an ideal heatsink (e.g. metal block)
- Typical Values: Due to the special conditions of the manufacturing processes of semiconductor devices, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.
- Testing temperature: $T_{\Delta} = 25^{\circ}C$
- Tolerance of Measure: Unless otherwise noted in drawing, tolerances are specified with ±0.1 and dimensions are specified in mm.
- ⁸⁾ **Tape and Reel**: All dimensions and tolerances are specified acc. IEC 60286-3 and specified in mm.



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